

General Description:

The GL5N04 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications. The package form is SOT-23-3L which accords with the RoHS standard.

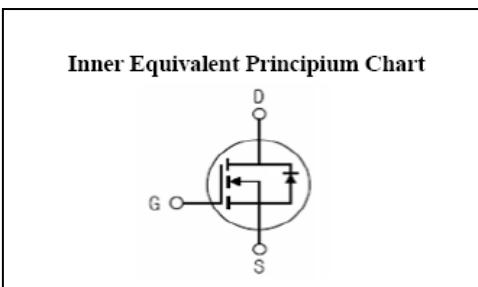
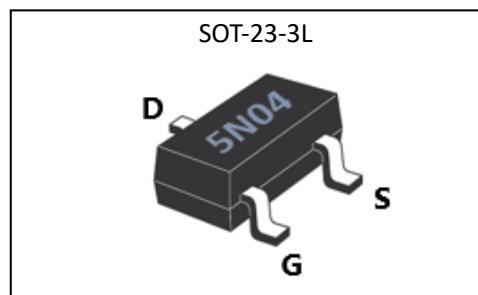
Features:

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Applications:

- PWM applications
- Load switch
- Power management

V _{DSS}	40	V
I _D	5	A
P _D	1.4	W
R _{DSON} TYPE	30	mΩ


Absolute (T_c = 25°C unless otherwise specified):

Symbol	Parameter	Rating	Units
V _{DSS}	Drain-to-Source Voltage	40	V
I _D	Continuous Drain Current	5	A
	Continuous Drain Current T _c = 70 °C	3.8	A
I _{DM} ^{a1}	Pulsed Drain Current	20	A
V _{GS}	Gate-to-Source Voltage	±20	V
dV/dt ^{a3}	Peak Diode Recovery dv/dt	5.0	V/ns
P _D	Power Dissipation	1.4	W
T _J , T _{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	°C
T _L	Maximum Temperature for Soldering	300	°C



GL5N04

GL Silicon N-Channel Power MOSFET

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	40	--	--	V
$\Delta V_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=-250\mu\text{A}$, Reference 25°C	--	0.1	--	$^\circ\text{C}$
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=40, V_{GS}=0\text{V}, T_a=25^\circ\text{C}$	--	--	1	μA
		$V_{DS}=32\text{V}, V_{GS}=0\text{V}, T_a=125^\circ\text{C}$	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+20\text{V}$	--	--	1	μA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-20\text{V}$	--	--	-1	μA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10\text{V}, I_D=2.5\text{A}$	--	30	45	$\text{m}\Omega$
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=2.5\text{A}$	--	40	60	$\text{m}\Omega$
$V_{GS(\text{TH})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	1.6	2.5	V
Pulse width $t_p \leq 380\mu\text{s}, \delta \leq 2\%$						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	$V_{DS}=15\text{V}, I_D = 5.0\text{A}$	10	--	--	S
C_{iss}	Input Capacitance		--	620	--	pF
C_{oss}	Output Capacitance	$V_{GS}=0\text{V}, V_{DS}=10\text{V}$ $f=1.0\text{MHz}$	--	130	--	
C_{rss}	Reverse Transfer Capacitance		--	50	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=1.0\text{A}, V_{DD}=15\text{V}$	--	7	--	ns
t_r	Rise Time		--	21	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	27	--	
t_f	Fall Time		--	7	--	
Q_g	Total Gate Charge	$I_D=5.0\text{A}, V_{DD} = 15\text{V}$	--	10	--	nC
Q_{gs}	Gate to Source Charge		--	1.9	--	
Q_{gd}	Gate to Drain ("Miller")Charge		--	2.8	--	



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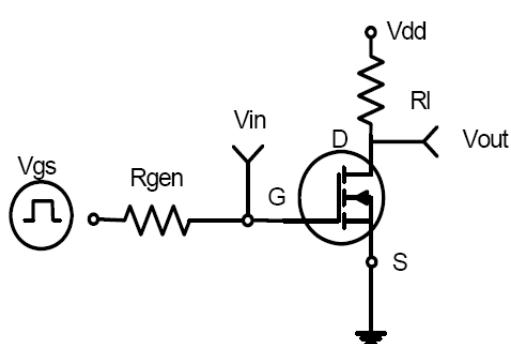
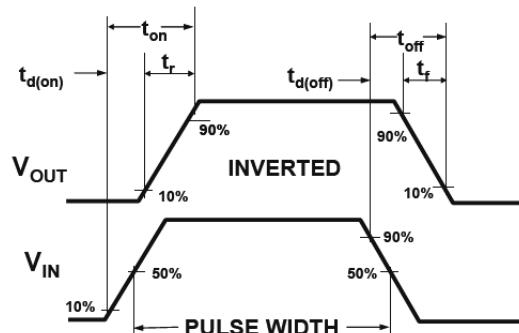
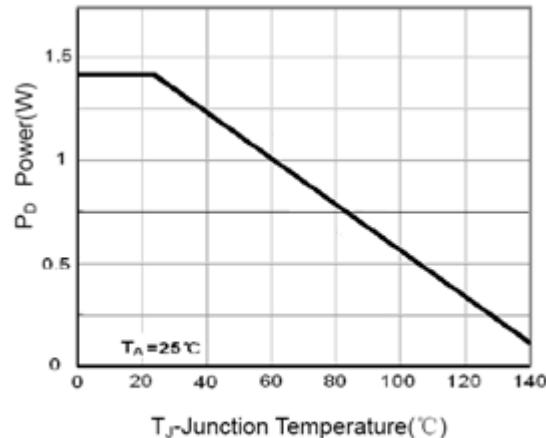
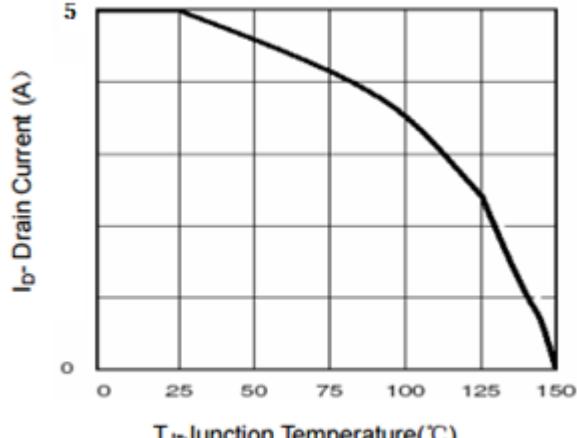
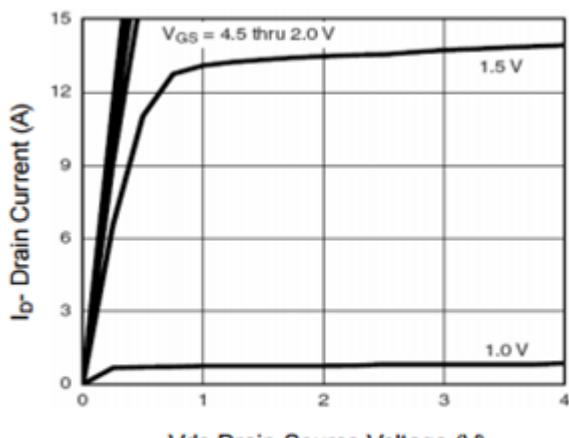
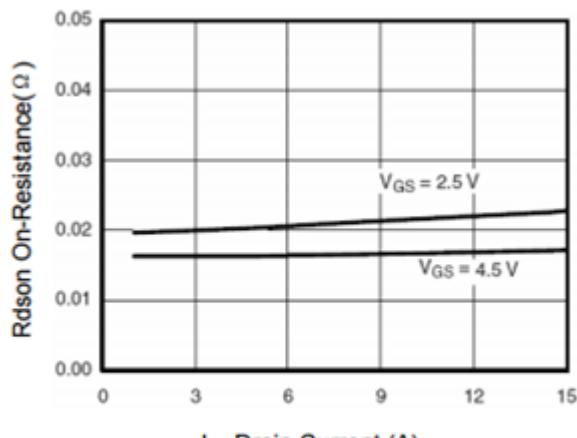
Source-Drain Diode Characteristics

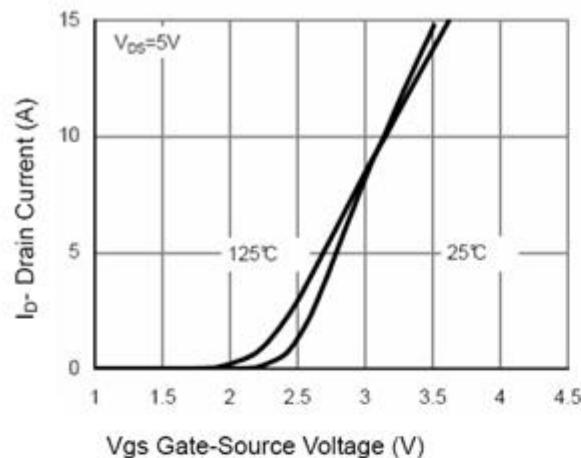
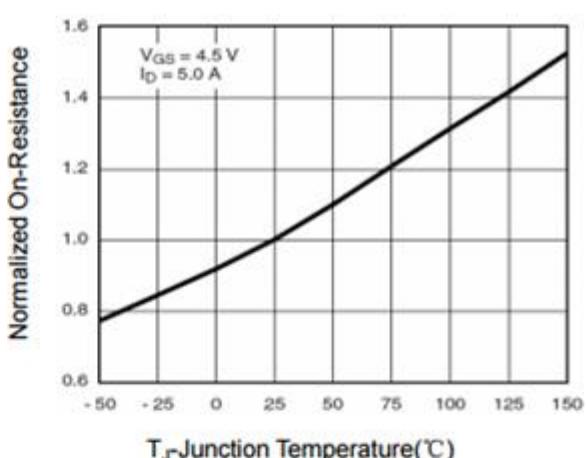
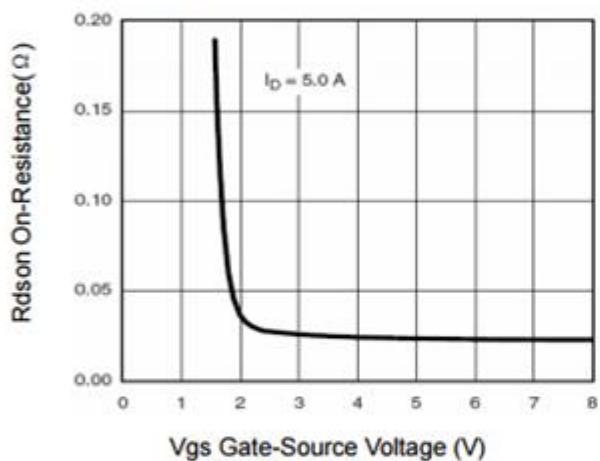
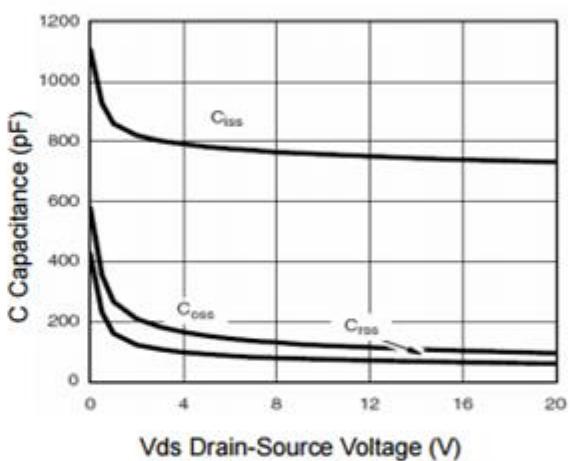
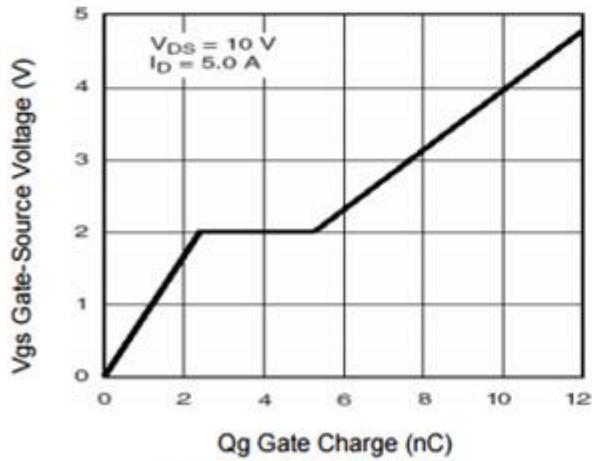
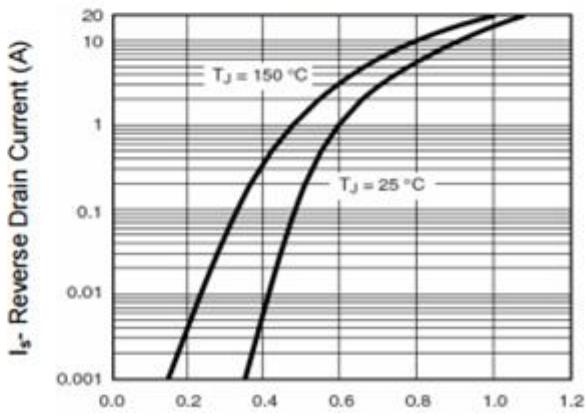
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I _S	Continuous Source Current (Body Diode)		--	--	5.0	A
I _{SM}	Maximum Pulsed Current (Body Diode)		--	--	20	A
V _{SD}	Diode Forward Voltage	I _S =5.0A, V _{GS} =0V	--	--	1.5	V
t _{rr}	Reverse Recovery Time	I _S =5.0A, T _j = 25°C	--	50	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt=100A/us, V _{GS} =0V	--	120	--	nC
Pulse width tp≤380μs, δ≤2%						

Symbol	Parameter	Typ.	Units
R _{θJA}	Junction-to-Ambient	90	°C/W

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a3}: I_{SD} = 7.0A, di/dt ≤ 100A/us, V_{DD} ≤ BV_{DS}, Start T_j = 25°C

Typical Electrical and Thermal Characteristics

Figure 1:Switching Test Circuit

Figure 2:Switching Waveforms

Figure 3 Power Dissipation

T_J-Junction Temperature(°C)
Figure 4 Drain Current

Figure 5 Output Characteristics

Figure 6 Drain-Source On-Resistance


Figure 7 Transfer Characteristics

Figure 8 Drain-Source On-Resistance

Figure 9 $R_{DS(on)}$ vs V_{GS}

Figure 10 Capacitance vs V_{DS}

Figure 11 Gate Charge

Figure 12 Source-Drain Diode Forward

